In the claims:

For the Examiner's convenience, all pending claims are presented below with changes shown in accordance with the mandatory amendment format.

- 1. (Previously Presented) An apparatus comprising:
 - a printed circuit board (PCB);
 - a connector mounted on the PCB; and

an integrated circuit (IC) package for insertion into the connector, the IC package having a plurality of input/output (I/O) lands with a varied pitch distance.

- 2. (Original) The apparatus of claim 1 wherein the plurality of lands include a vertical pitch having a first distance and a horizontal pitch having a second distance.
- 3. (Original) The apparatus of claim 1 wherein the connector includes a plurality of contacts having a varied pitch distance to match the plurality of lands.
- 4. (Original) The apparatus of claim 3 wherein the PCB comprises a plurality of land pads having a varied pitch distance to match the plurality of contacts.
- 5. (Original) The apparatus of claim 4 wherein the PCB comprises a plurality of traces coupled to the plurality of land pads.
- 6. (Original) The apparatus of claim 1 wherein the PCB is a motherboard.
- 7. (Original) The apparatus of claim 1 wherein the connector is a zero insertion force (ZIF) connector.

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- 8. (Original) The apparatus of claim 1 wherein the IC package is a land grid array (LGA).
- 9. (Previously Presented) An apparatus comprising:

a printed circuit board (PCB);

a connector mounted on the PCB; and

an integrated circuit (IC) package for insertion into the connector, the IC package having a plurality of input/output (I/O) pins with a varied pitch distance.

- 10. (Original) The apparatus of claim 9 wherein the plurality of pins include a vertical pitch having a first distance and a horizontal pitch having a second distance.
- 11. (Original) The apparatus of claim 10 wherein the PCB comprises a plurality of pin pads having a varied pitch distance to match the plurality of pins.
- 12. (Original) The apparatus of claim 9 wherein the IC package is a pin grid array (PGA).
- 13. (Previously Presented) An integrated circuit (IC) comprising:

 a plurality of input/output pins (I/O) connectors having a varied pitch distance.
- 14. (Original) The IC of claim 13 wherein the plurality of I/O connectors include a vertical pitch having a first distance and a horizontal pitch having a second distance.
- 15. (Original) The IC of claim 13 wherein the plurality of I/O connectors comprise lands.

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